



# N-Channel 1.25-W, 2.5-V MOSFET

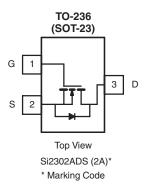
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)			
20	0.060 at $V_{GS} = 4.5 \text{ V}$	2.4			
	0.115 at V <sub>GS</sub> = 2.5 V	2.0			

#### **FEATURES**

• Halogen-free Option Available







Ordering Information: Si2302ADS-T1

Si2302ADS-T1-E3 (Lead (Pb)-free)

Si2302ADS-T1-GE3 (Lead (Pb)-free and Halogen-free)

<b>ABSOLUTE MAXIMUM RATINGS</b>	T <sub>A</sub> = 25 °C, unle	ess otherwise	noted			
Parameter		Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20		V	
Gate-Source Voltage		$V_{GS}$	± 8			
Continuous Dunis Courset /T 450 °C\d	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	2.4	2.1	۸	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		1.9	1.7		
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	10		Α	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	0.94	0.6		
Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.9	0.7	w	
rower dissipation	T <sub>A</sub> = 70 °C		0.57	0.46		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol Typical Maximus		Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 5 s	- R <sub>thJA</sub>	115	140	°C/W	
	Steady State		140	175	]	

#### Notes:

a. Surface Mounted on FR4 board.

For SPICE model information via the Worldwide Web: http://www.vishay.com/www/product/spice.htm

\* Pb containing terminations are not RoHS compliant, exemptions may apply

## **Si2302ADS**

# Vishay Siliconix



<b>SPECIFICATIONS</b> T <sub>A</sub> = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 10 \mu\text{A}$	20			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 50 \mu A$	0.65	0.95	1.2	v	
Gate Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	1	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			0.1	μΑ	
	IDSS	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			2.0		
On-State Drain Current <sup>a</sup>		$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	6			A	
On-State Drain Guiterit	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 2.5 \text{ V}$	4				
Drain-Source On-Resistance <sup>a</sup>	В	$V_{GS} = 4.5 \text{ V}, I_D = 3.6 \text{ A}$		0.045	0.060 <sup>b</sup>	Ω	
Dialii-Source Off-nesistance	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, I_D = 3.1 \text{ A}$		0.070	0.115		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 5 \text{ V}, I_{D} = 3.6 \text{ A}$		8		S	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 0.94 A, V <sub>GS</sub> = 0 V		0.76	1.2	V	
Dynamic							
Total Gate Charge	$Q_g$			4.0	10	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 3.6 \text{ A}$		0.65			
Gate-Drain Charge	$Q_{gd}$			1.5			
Input Capacitance	C <sub>iss</sub>			300			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		120		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			80			
Switching							
Turn-On Delay Time	t <sub>d(on)</sub>			7	15		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 2.8 $\Omega$		55	80	- ns	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong 3.6$ A, $V_{GEN}=4.5$ V, $R_g=6$ $\Omega$		16	60		
Fall Time	t <sub>f</sub>			10	25		

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; PW  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

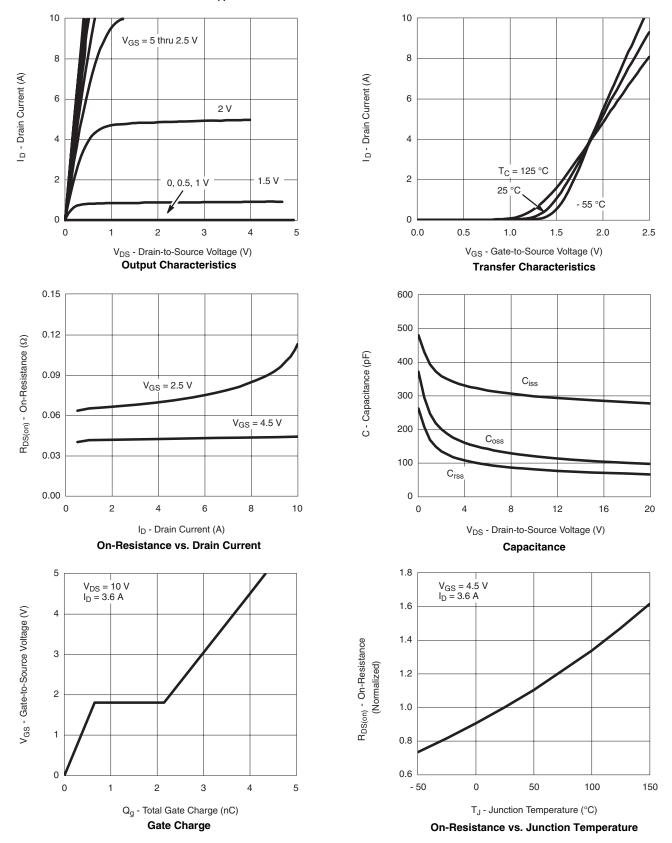
b. Effective for production 10/04.







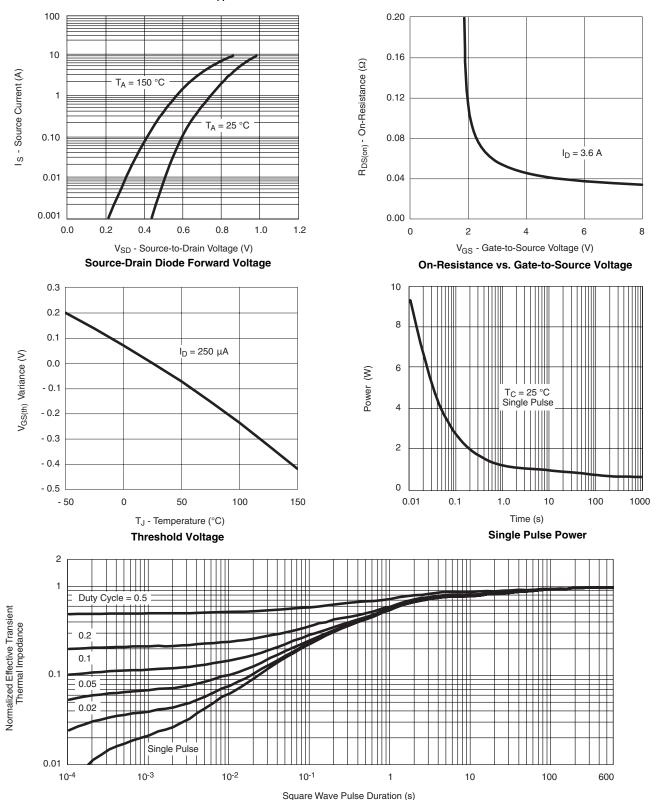
#### **TYPICAL CHARACTERISTICS** $T_A = 25$ °C, unless otherwise noted



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Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="http://www.vishay.com/ppg?71831">http://www.vishay.com/ppg?71831</a>.

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Document Number: 91000 www.vishay.com Revision: 08-Apr-05